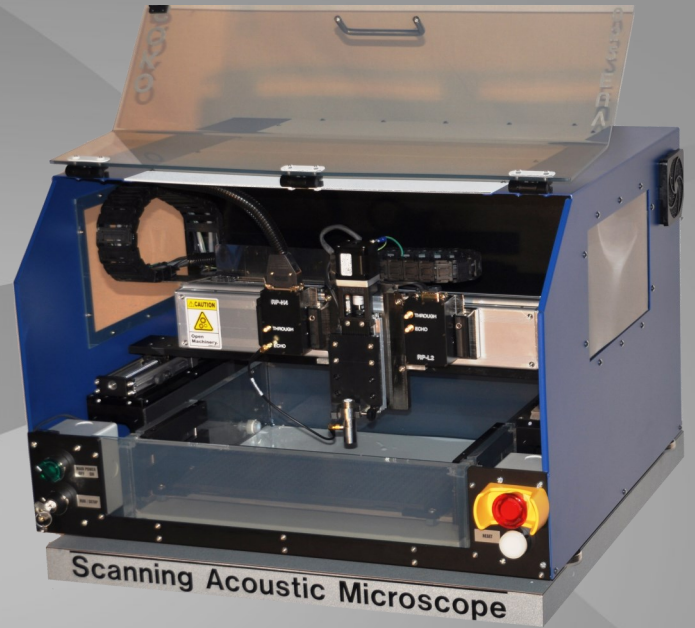


Multi-Gating

Virtual Rescanning

Thickness Measurements



VUE 250-P

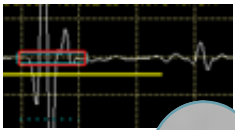
SCANNING ACOUSTIC MICROSCOPY

Semiconductor Package Failure Analysis

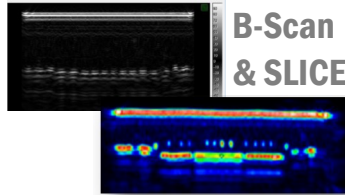
voids · disbonds · cracks · delamination · internal defects

Included Software Modes:

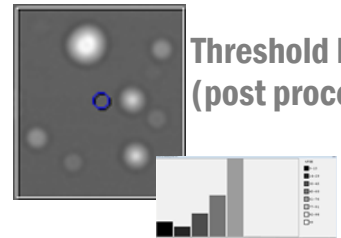
- Basic (user friendly)
- Advanced (detailed analysis)
- Offline Analysis (virtual scanning)



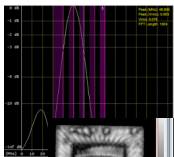
Real-time A-Scan & A-Scan Capture



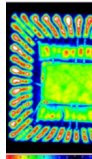
B-Scan & SLICE



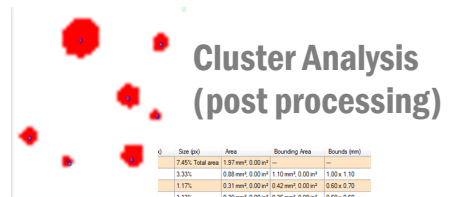
Threshold Mapping (post processing)



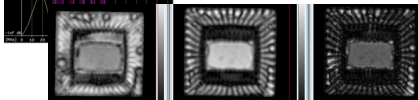
Frequency Domain Imaging (FFT)



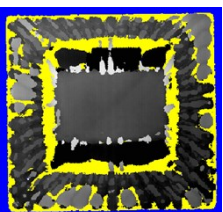
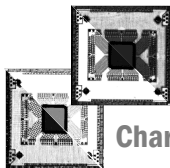
C-Scan with Multi-gate, SALI, & SALI Groups



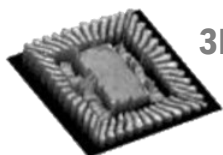
Cluster Analysis (post processing)



Scan Math Before and After Reflow Characterization



Advanced Time-of-Flight & Thickness Measurements



3D Imaging



Void Gating (real-time)

SPECS

Maintenance Free Scan Axis

Motor: Linear Servo
 Max Velocity: 500 mm/s
 Accuracy & Repeatability: +/- 1.0 micron
 Scan Envelope: 250 mm

Low Maintenance Step Axis

Step Envelope: 150 mm

Low Maintenance Focus Axis

Focus Envelope: 35 mm

Dimensions

0.64 m x 0.61 m x 0.5 m (WDH)
 52 kg

Customer Interface

Dual 22" HD LED Monitors

Fixtures

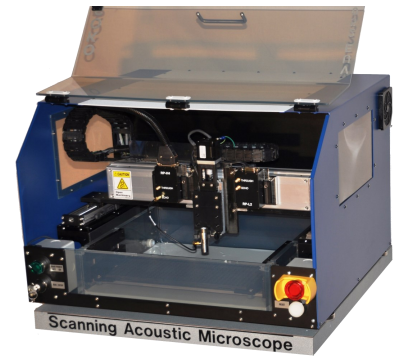
Tray Fixture
Optional Through Transmission Bracket
 LED illumination

Instrumentation

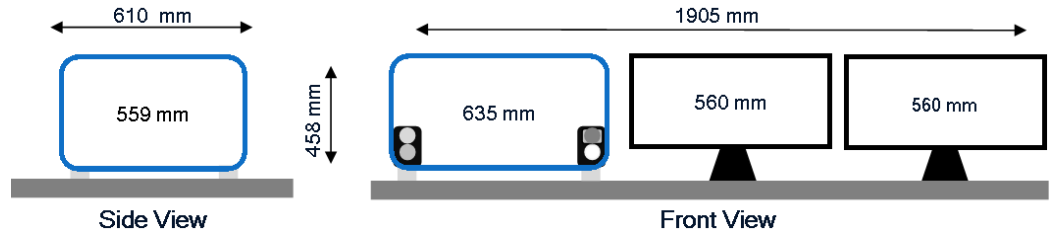
Digital Pulser Receiver
 Up to 4 GHz Digitizer

Scan Area

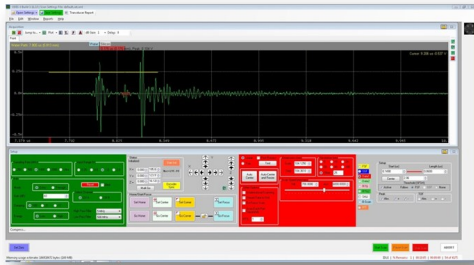
Partial JEDEC Tray



WORKSPACE



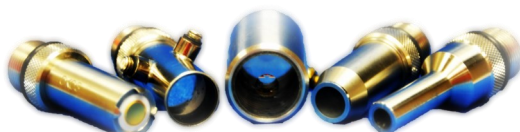
OKOS Digital Imaging System (ODIS)



ODIS is the latest Acoustic Microscopy software with rich technical content built on current platforms and industry feedback. It includes both time domain and frequency domain imaging in real-time. Advanced analysis is provided through quantitative tools for measurement and classification of parts. The Analysis version of ODIS allows non-scanning computers to

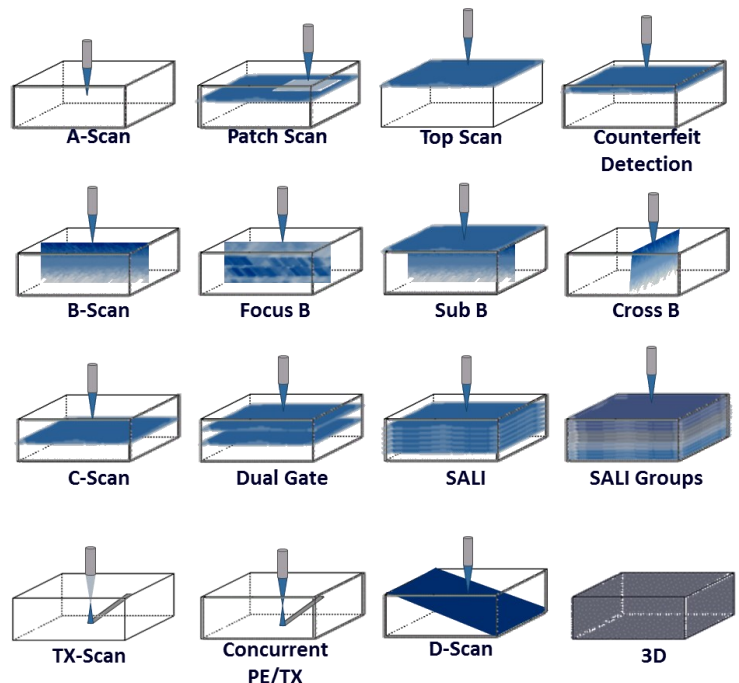
- | | |
|-----------------------|--------------------|
| Counterfeit Detection | Product Inspection |
| Product Reliability | Quality Control |
| Process Validation | Failure Analysis |
| Vendor Qualification | R&D |

virtually scan, view, and analyze data for simultaneous real-time analysis or post collection review. Previously undetected flaws can now be imaged with poled peak analysis.



Application Specific Transducers

for the highest quality resolution. Multiple transducer designs for enhanced scan capability.



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